

# TI Designs: TIDEP-0067 66AK2Gx DSP + ARM 处理器电源解决方案参考设计



## TI Designs

此 TI 设计是一款基于 K2G 多内核 DSP + ARM® 片上系统 (SoC) 和配套 TPS65911x 电源管理集成电路 (PMIC) 的电源参考平台。该电源解决方案设计还包含支持 12V 输入的第一级降压转换器和用于 DDR3L 存储器的 DDR 终端稳压器。该参考设计经过了测试，包括硬件参考 (EVM)、软件 (处理器 SDK) 和测试数据。

## 设计资源

<a href="#">TIDEP0067</a>	工具文件夹 (包含设计文件)
<a href="#">66AK2G12</a>	产品文件夹
<a href="#">TPS65911</a>	产品文件夹
<a href="#">TPS54620</a>	产品文件夹
<a href="#">TPS54429</a>	产品文件夹
<a href="#">K2G 通用 EVM</a>	EVM 工具文件夹
<a href="#">K2G 1GHz GP EVM</a>	EVM 工具文件夹
<a href="#">适用于 K2G 的处理器 SDK</a>	下载软件

## 特性

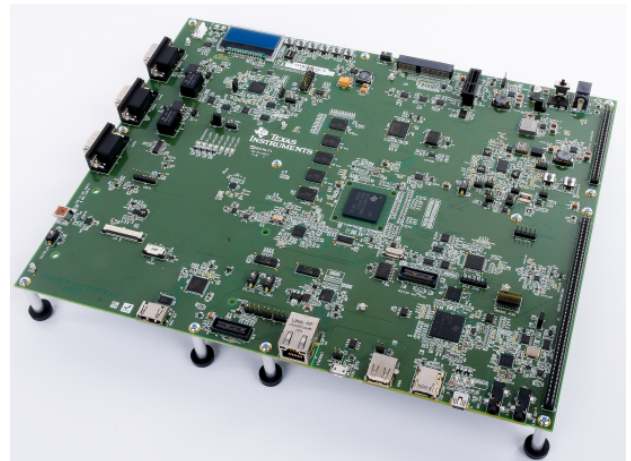
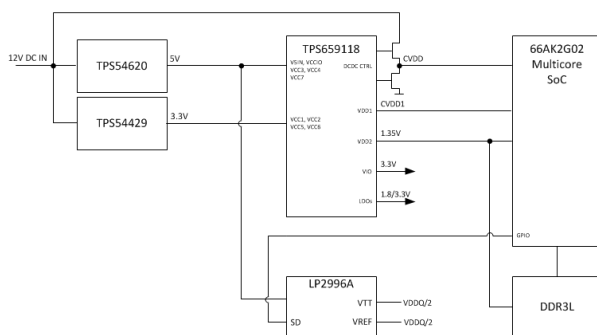
- TPS54620 和 TPS54429: 用于将 12V 输入转换为 3.3V 和 5V 输出的第一级降压转换器。
- TPS65911x 配套 PMIC, 支持 SoC 和 DDR3L 存储器所需的电源定序和电源。
- TPS65911x 具有集成式实时时钟 (RTC), 适用于时间关键型应用。
- LP2996A DDR3L 终端稳压器。

## 应用

- 汽车音频放大器
- 家用音频
- 专业音频
- 电源保护



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### 3 K2G EVM Overview

The K2G GP EVM is intended to exercise the key interfaces on the K2G device. The K2G GP EVM includes the following features:

- Memory
  - 2 GB of DDR3L with ECC (32-bit data + 4-bit ECC)
  - 512 Mbit of QSPI Flash
  - 2 Gbit of NAND Flash
  - 128 Mbit of SPI Flash
  - 128 kByte of 12C EEPROM for Boot support from 12 C
  - 16 GByte eMMC
  - Micro-SD Card slot (32 GB micro-SD card included)
- Connectivity
  - Gbit Ethernet: RGMII through Micrel KSZ9031 PHY RJ45 jack
  - USB 2.0 × 2: Micro A/B connector, Host connector
  - PCIe Gen 2: Single lane card slot (root complex only)
  - COM8 connector for use with WiLink 8 modules
- Display
  - 4.3" Touch LCD display (sold seperately)
  - HDMI Tx
- Audio
  - AIC3106 stereo code
  - 3.5 mm stereo jack ×2 supports stereo analog input and output
  - All McASP signals routed to audio expansion connector
- General Purpose Serial
  - SPI and 12C ports not already used for memory, or control are routed to serial expansion connector
  - UART through RS232 chip and DB9 connector, UART over USB
- Automotive
  - MLB supported through expansion connector
  - DCAN supported through transceivers, DB9 connectors
- Emulation
  - Onboard XDS200 through mini-USB connector
  - MIPI-60 header for external emulators
  - TRACE is supported with some caveats (resistor-muxed with display signals)
- Power
  - Provided through TPS65911x PMIC – factory-programmed with K2G power-up sequence
    - 3 step-down DC–DC converters
    - 8 LDOs
    - 12C and enable signals

- Board Management Controller
  - Mainly intended for automated testing; not intended for end-products
  - May control boot modes, power-up, and more
  - Character display for system status
- Clocking
  - K2G is unique among K2 devices because the K2G generates most clocks internally, including audio frequency clocks. DDR, USB, Ethernet, and more. Clocks may be generated internally. This is the default mode on the EVM.
  - A CDCM6209 is also included and generates SYSCLK, DDR ref clock, USB clk, and PCIe clock.

图 2 shows the K2G general purpose EVM.

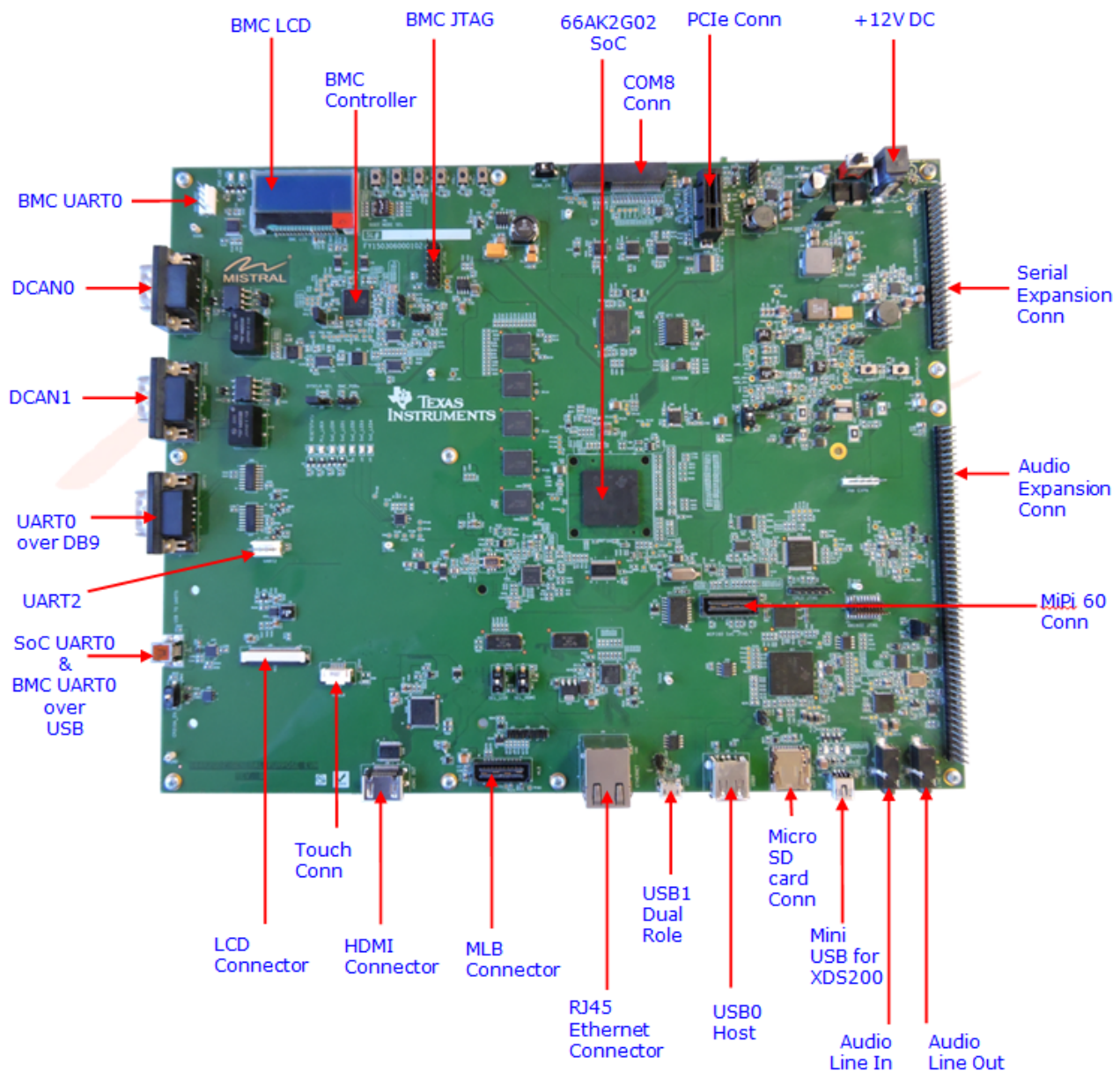


图 2. K2G General Purpose EVM

## 4 Software

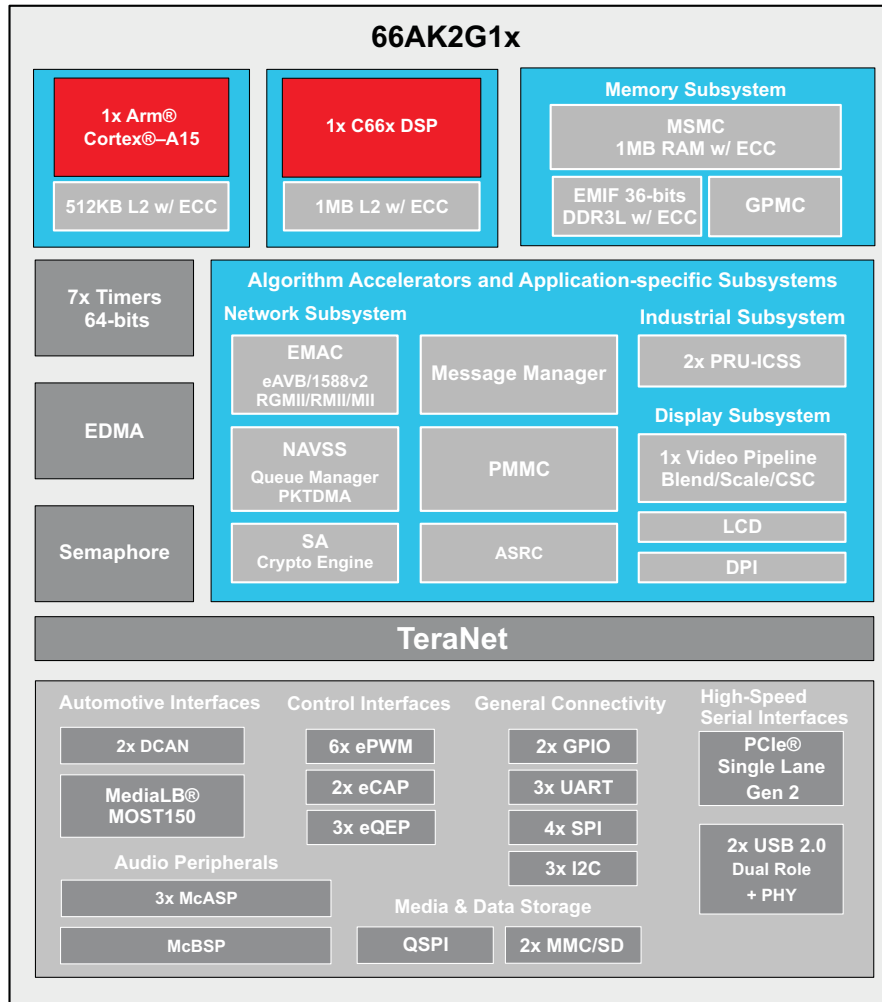
Software for the K2G EVM is available by downloading the Processor SDK.

## 5 K2G EVM

The 66AK2Gx SoC supports the following features:

- Processor Cores and Memory
  - ARM Cortex A15 up to 1000 MHz
    - 32 KB L1D, 32 KB L1P, 512 KB, L2 cache
  - C66x DSP up to 1000 MHz
    - 32 KB L1D, 32 KB L1P, 1 MB L2
  - ECC on all memory
- Industrial and Control Peripherals
  - 2 Industrial Communication Subsystems enable cut through, real-time and low latency industrial Ethernet protocols
  - Programmable real-time I/O enables versatile field bus and control interfaces
- Security and Crypto
  - Standard secure boot with customer programmable OTP keys
  - Crypto
  - Package
    - 21 × 21 mm, 0.8-mm pitch BGA 625 pins

图 3 shows the 66AK2G12 diagram.



intro\_001

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图 3. 66AK2G12 Diagram

## 6 TPS65911x Power Management Integrated Circuit (PMIC)

The TPS65911x is an integrated power management IC configured to operate with the 66AK2Gx SoC, combining three switch-mode buck converters, one switch-mode buck controller, and 8 linear regulators into a single BGA package. The PMIC handles power-supply sequencing and reset conditions, provides GPIO outputs for enabling external regulators or switches, and accepts i2c instructions from the processor for features such as voltage scaling and interrupt masking of various event or fault notifications. The TPS659118 is optimized to power a 66AK2G02 system, utilizing a one-time-programmable (OTP) memory configured with boot voltages, power sequencing, and other default conditions. The TPS65911A is optimized to power a 66AK2G12 system. The PMIC and processor must be connected correctly in order to meet the defined voltage, current, and sequencing requirements of the processor. A detailed lock diagram of the power management solution for the 66AK2Gx using the TPS65911x is shown in [图 4](#). The *TPS659118 User's Guide to Power 66AK2G02* ([SWCU176](#)) describes these connections, as well as the OTP settings defined within the PMIC. The *TPS65911A User's Guide to Power 66AK2G12* ([SWCU176](#))

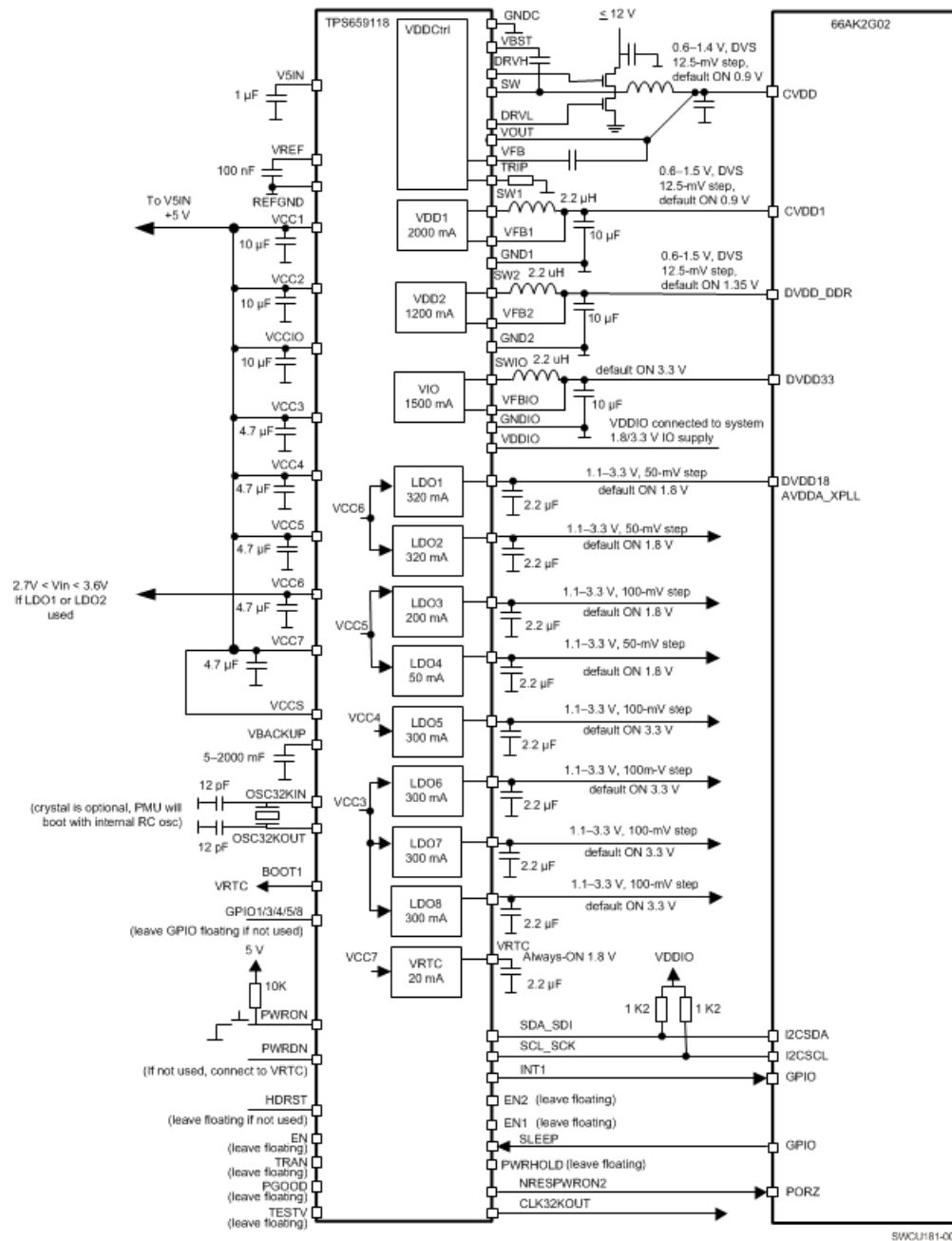


图 4. TPS659118 PMIC with 66AK2G02



## 7 Test Data

### 7.1 Power-Up Sequence Specification

图 5 shows the TPS65911x power-up sequencing timing.

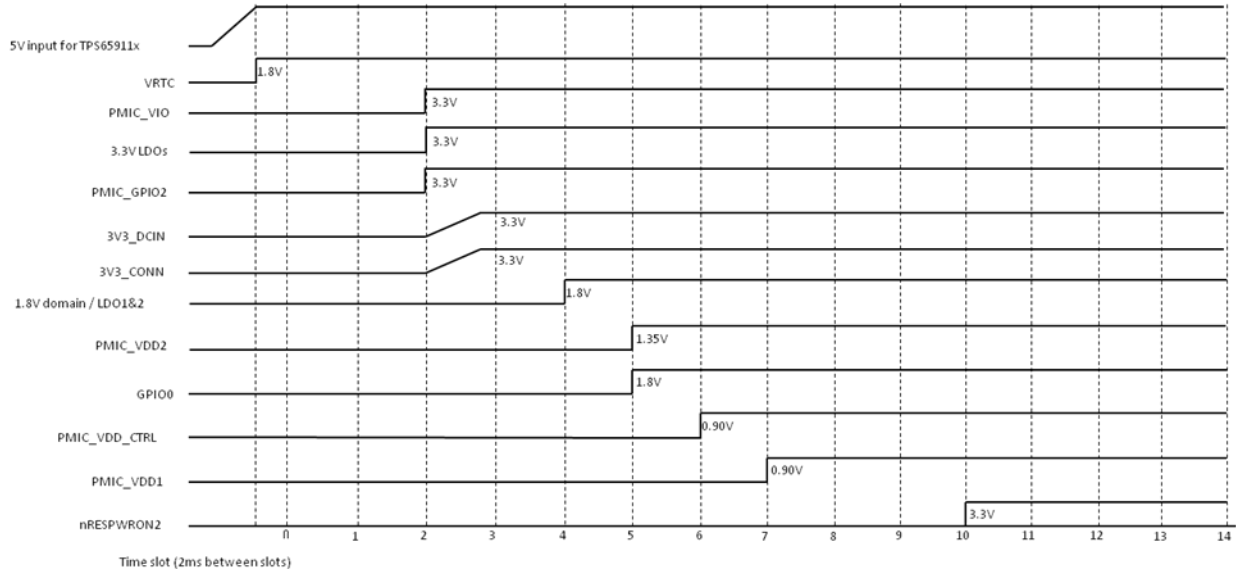


图 5. TPS65911x Power Sequencing

## 7.2 Power-Up Sequence Waveforms

The following waveforms demonstrate the power-on of the TPS65911x as required by the 66AK2Gx.

图 6 shows the power-on sequence for each of the output voltage rails and nRESPWRON2 signal respectively. The 3.3 V, 1.8 V, 1.35 V, CVDD, and CVDD1 rails turn sequentially and the nRESPWRON2 signal goes HIGH after all rails are ON.

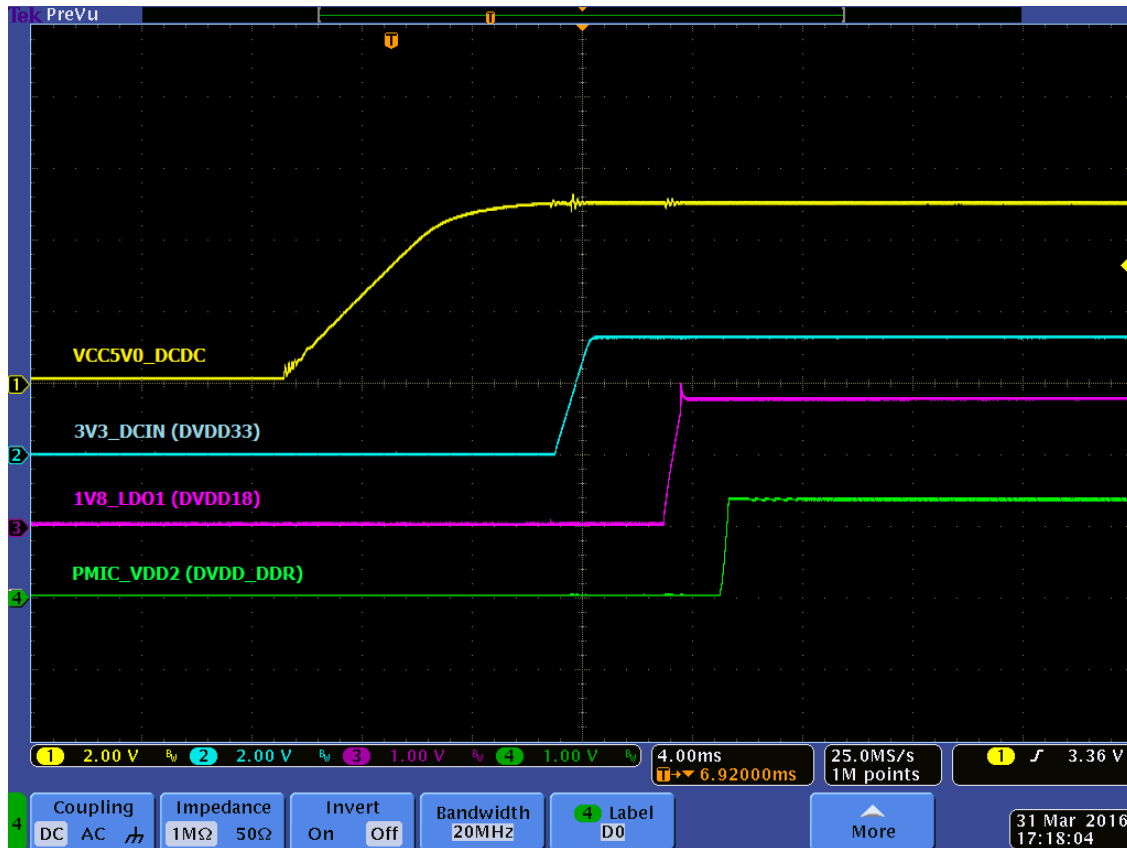


图 6. Power-On Sequence for the TPS65911x

表 1 lists the delay time for the 3.3 V, 1.8 V, and 1.35 V processor power supplies.

表 1. Delay Time for the 3.3 V, 1.8 V, and 1.35 V Processor Power Supplies

PLOT	EXPECTED TIMING	ACTUAL TIMING
1 to 2	N/A	10.0 ms
2 to 3	4.0 ms	4.0 ms
2 to 4	6.0 ms	6.0 ms
3 to 4	2.0 ms	2.0 ms

图 7 shows the power-on sequence for the TPS65911x with nRESPWRON2.



图 7. Power-On Sequence for the TPS65911x With nRESPWRON2

表 2 lists the delay time for the CVDD and CVDD1 processor power supplies and power on reset (POR) signal.

表 2. Delay Time for the CVDD and CVDD1 Processor Power Supplies and Power On Reset (POR) Signal

PLOT	EXPECTED TIMING	ACTUAL TIMING
1 to 2	N/A	18.4 ms
2 to 3	2.0 ms	2.0 ms
2 to 4	8 ms	8.0 ms
3 to 4	6 ms	6 ms

图 8 shows the 3.3 V VIO buck converter, 3.3 V LDO5 and 1.8 V LDO1 of the TPS65911x. The 3.3 V PMIC\_VIO buck converter and the 3.3 V\_LDO turn ON simultaneously.

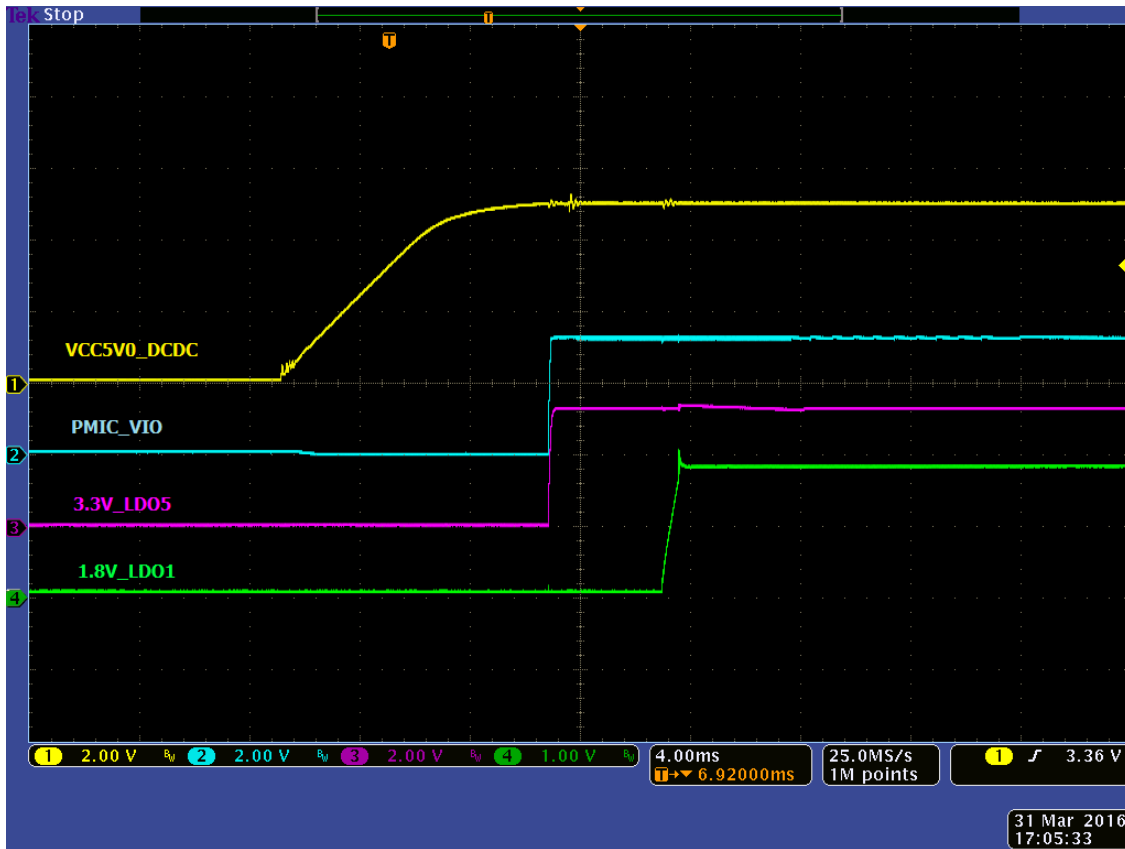


图 8. Power-On Sequence for the TPS65911x Voltage Rails

## 8 Design Files

To download the design files for TIDEP0067, see the design files at <http://www.ti.com/tool/TIDEP0067>.

### 8.1 商标

Arm is a registered trademark of ARM Limited.

## 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

<b>Changes from Original (May 2016) to A Revision</b>	<b>Page</b>
• 添加了 66AK2G12 产品文件夹。.....	1
• 添加了指向 EVMK2GX 工具文件夹 (1GHz K2G GP EVM) 的链接。.....	1
• Changed "at 600 MHz" to "up to 1000 MHz" for both Cortex-A15 and C66x cores. ....	5
• Changed 66AK2G02 block diagram to 66AK2G12 block diagram.....	6
• Added distinction between TPS659118 and TPS65911A.....	7

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